

Build Up HDI (Standard)											
HDI10_1+8+1_1,30_17.5_engl		10 - Layers									
		Core: 0,15 mm Cu 17.5/17.5 µm									
WE-Article No.:		1 + 8 + 1									
Customer:											
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements		
Customer	WE							[µm]	[µm]		
	TOP/VS				Foil	12 µm	<sup>1)</sup>		12		
								1 x 1080	66		
	2					17.5 µm			16		
					0,150 mm				150		
	3					17.5 µm		2 x 1080	134		
									16		
	4					17.5 µm			16		
					0,150 mm				150		
	5					17.5 µm			16		
					2 x 1080	134					
	6		17.5 µm			16					
		0,150 mm				150					
	7		17.5 µm			16					
					2 x 1080	134					
	8		17.5 µm			16					
		0,150 mm				150					
	9		17.5 µm			16					
					1 x 1080	66					
	BOT/RS	Foil	12 µm	<sup>1)</sup>		12					
					1) copper thickness outer layers: appr. 55 µm						
					total material thickness: 1286						
					Note: Lamination thickness for Prepregs depending on layout characteristics.						
final lamination thickness:		1,30	+/-	0,10	mm	Date:		Engineer:			
thickness with electro plated Cu:		1,39	+/-	0,13	mm						
total thickness with soldermask		1,45	+/-	0,15	mm						
customer requirement			+/-		mm	point:					
prepared: on 27.03.2006 by S. Keller		checked: on 04.05.2006 by M.Kress		approved: on 04.05.2006 by R. Schönholz		revision 00		page: 5+			